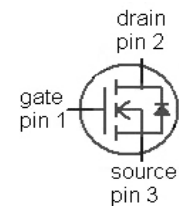
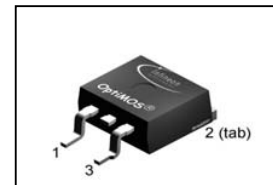


OptiMOS[®] Power-Transistor
Features

- N-channel Logic Level - Enhancement mode
- Automotive AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- **Green package (lead free)**
- Ultra low Rds(on)
- 100% Avalanche tested

Product Summary

V_{DS}	55	V
$R_{DS(on),max}$ (SMD version)	64	mΩ
I_D	19	A

PG-TO252-3-11


Type	Package	Marking
IPD15N06S2L-64	PG-TO252-3-11	2N06L64

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_C=25\text{ °C}, V_{GS}=10\text{ V}$	19	A
		$T_C=100\text{ °C}, V_{GS}=10\text{ V}^{(1)}$	13	
Pulsed drain current ⁽¹⁾	$I_{D,pulse}$	$T_C=25\text{ °C}$	76	
Avalanche energy, single pulse	E_{AS}	$I_D=15\text{ A}$	43	mJ
Gate source voltage	V_{GS}		±20	V
Power dissipation	P_{tot}	$T_C=25\text{ °C}$	47	W
Operating and storage temperature	T_j, T_{stg}		-55 ... +175	°C
IEC climatic category; DIN IEC 68-1			55/175/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics

Thermal resistance, junction - case	R_{thJC}		-	-	3.2	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}		-	-	100	
SMD version, device on PCB	R_{thJA}	minimal footprint	-	-	75	
		6 cm ² cooling area ²⁾	-	-	50	

Electrical characteristics, at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified
Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=1\text{ mA}$	55	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=14\text{ }\mu\text{A}$	1.2	1.6	2.0	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=55\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ }^\circ\text{C}$	-	0.01	1	μA
		$V_{DS}=55\text{ V}, V_{GS}=0\text{ V}, T_j=125\text{ }^\circ\text{C}^{1)}$	-	1	100	
Gate-source leakage current	I_{GSS}	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	-	1	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{ V}, I_D=13\text{ A}$	-	61	85	m Ω
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=13\text{ A}$	-	47	64	m Ω

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics¹⁾

Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=25\text{ V},$ $f=1\text{ MHz}$	-	354	-	pF
Output capacitance	C_{oss}		-	103	-	
Reverse transfer capacitance	C_{rss}		-	38	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=30\text{ V}, V_{GS}=10\text{ V},$ $I_D=15\text{ A}, R_G=20\ \Omega$	-	4	-	ns
Rise time	t_r		-	14	-	
Turn-off delay time	$t_{d(off)}$		-	21	-	
Fall time	t_f		-	12	-	

Gate Charge Characteristics¹⁾

Gate to source charge	Q_{gs}	$V_{DD}=44\text{ V}, I_D=19\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	1	1.5	nC
Gate to drain charge	Q_{gd}		-	4	5	
Gate charge total	Q_g		-	11	13	
Gate plateau voltage	$V_{plateau}$		-	3.8	-	V

Reverse Diode

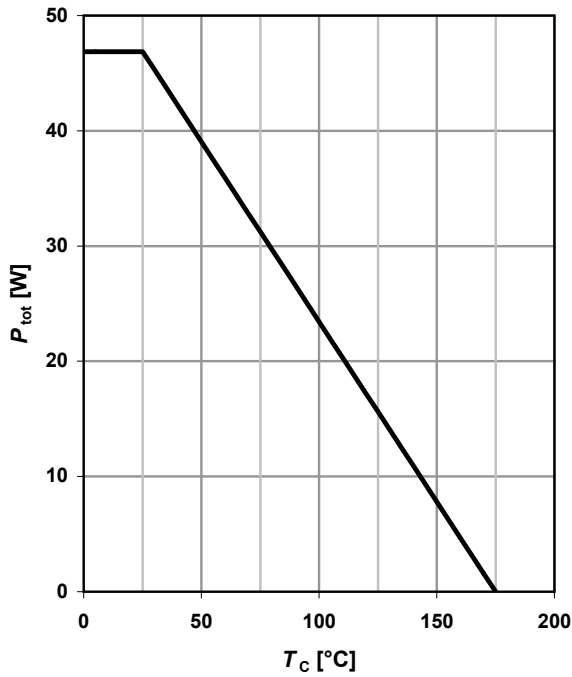
Diode continuous forward current ¹⁾	I_S	$T_C=25\text{ }^\circ\text{C}$	-	-	19	A
Diode pulse current ¹⁾	$I_{S,pulse}$		-	-	76	
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=15\text{ A},$ $T_j=25\text{ }^\circ\text{C}$	-	0.93	1.3	V
Reverse recovery time ¹⁾	t_{rr}	$V_R=30\text{ V}, I_F=I_S,$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	34	-	ns
Reverse recovery charge ¹⁾	Q_{rr}	$V_R=30\text{ V}, I_F=I_S,$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	32	-	nC

¹⁾ Defined by design. Not subject to production test.

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

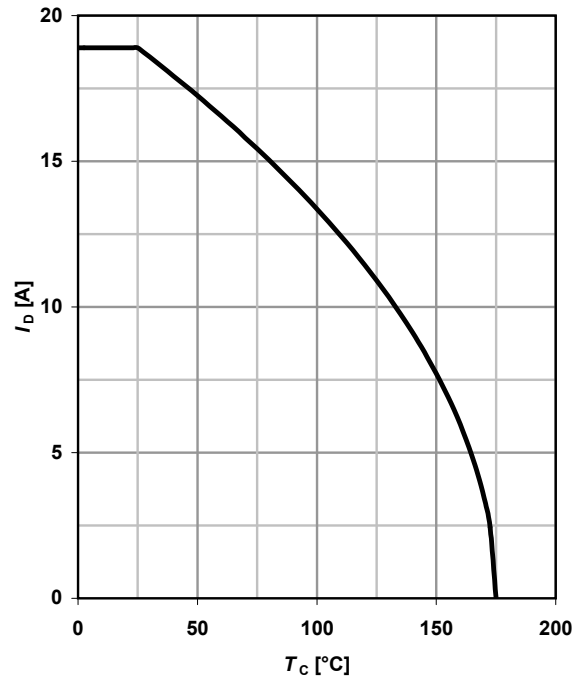
1 Power dissipation

$P_{tot} = f(T_C); V_{GS} \geq 4 \text{ V}$



2 Drain current

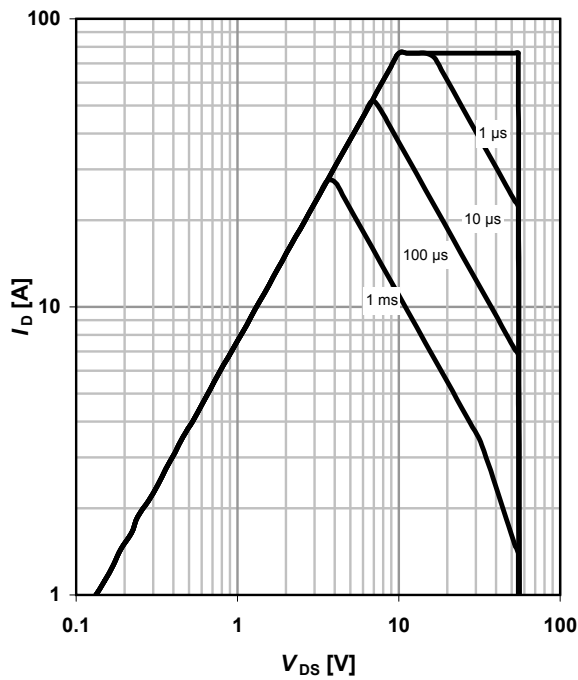
$I_D = f(T_C); V_{GS} \geq 10 \text{ V}$



3 Safe operating area

$I_D = f(V_{DS}); T_C = 25 \text{ °C}; D = 0$

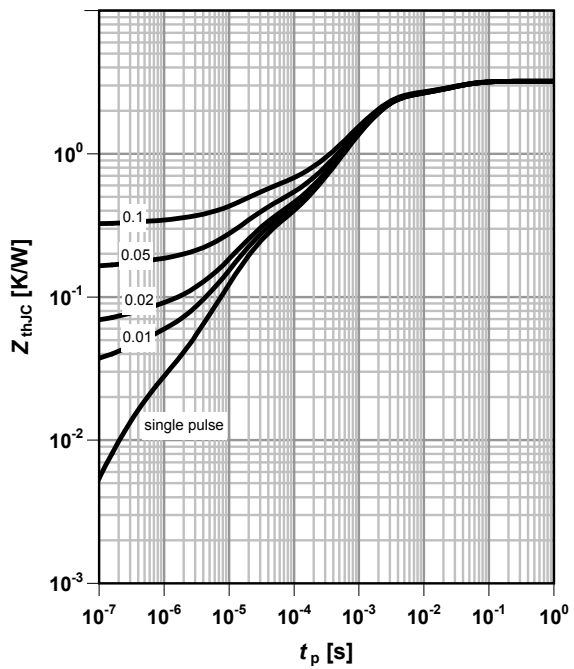
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

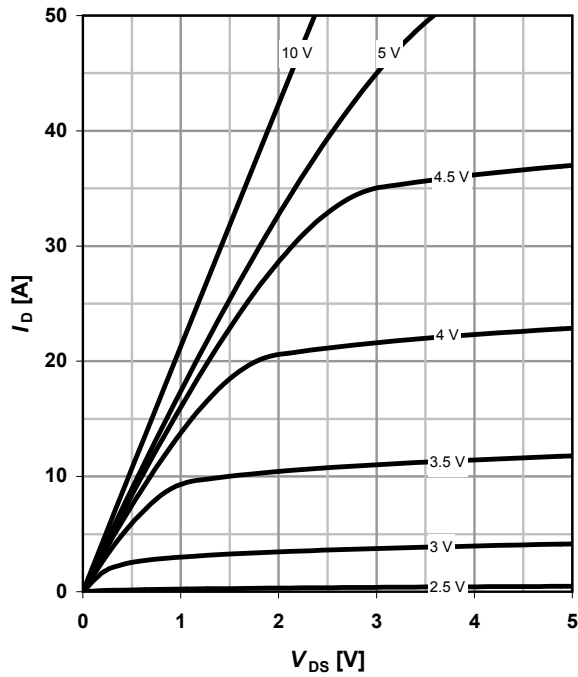
parameter: $D = t_p/T$



5 Typ. output characteristics

$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$$

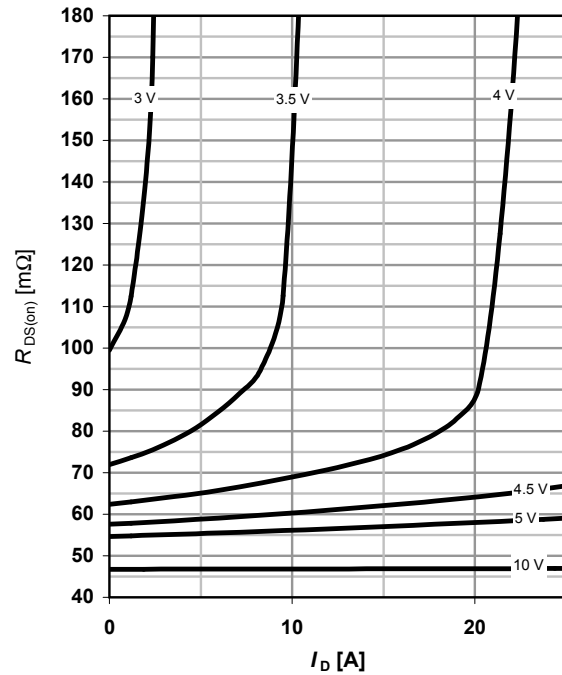
parameter: V_{GS}



6 Typ. drain-source on-state resistance

$$R_{DS(on)} = f(I_D); T_j = 25^\circ\text{C}$$

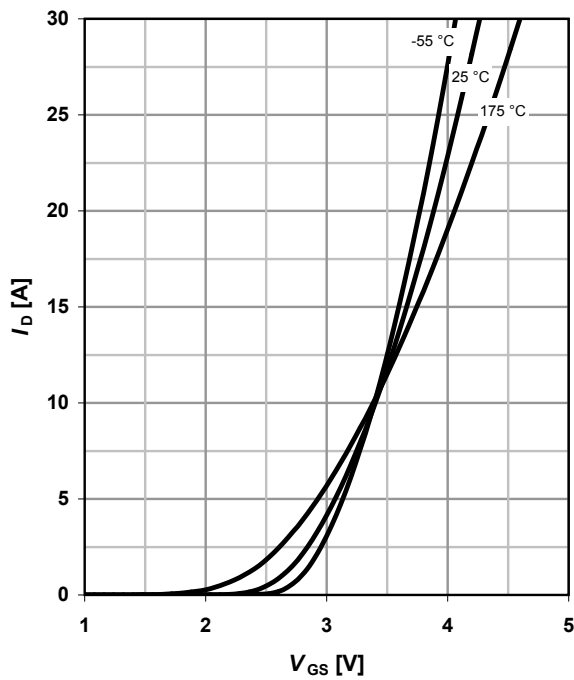
parameter: V_{GS}



7 Typ. transfer characteristics

$$I_D = f(V_{GS}); V_{DS} = 5\text{V}$$

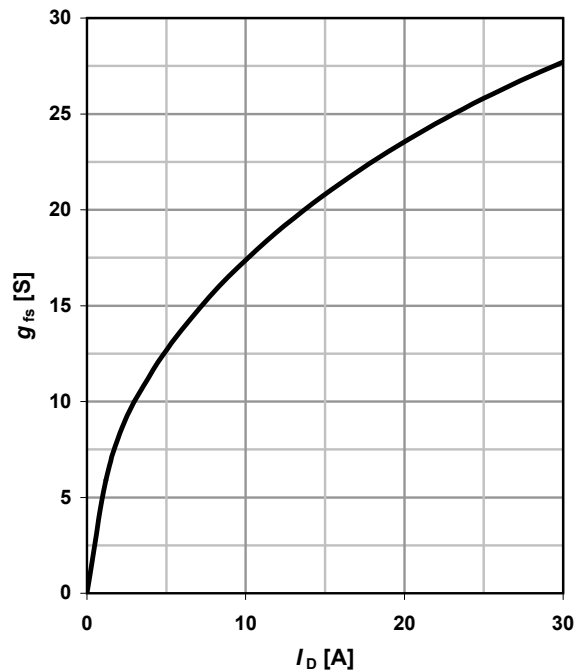
parameter: T_j



8 Typ. Forward transconductance

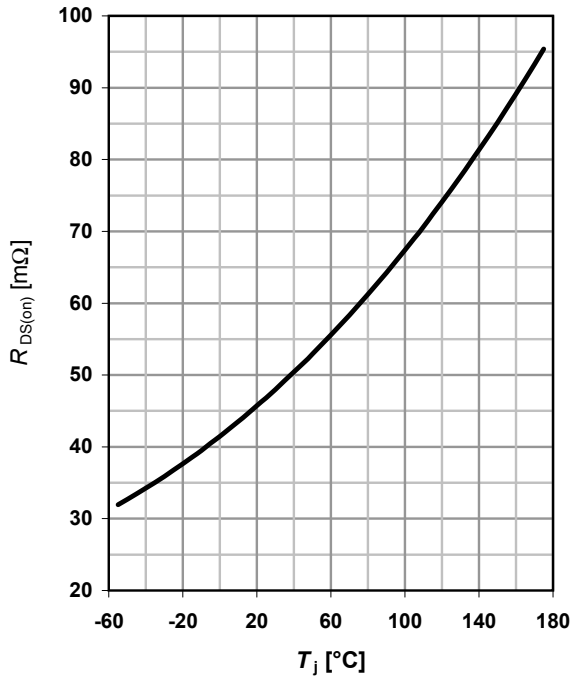
$$g_{fs} = f(I_D); T_j = 25^\circ\text{C}$$

parameter: g_{fs}

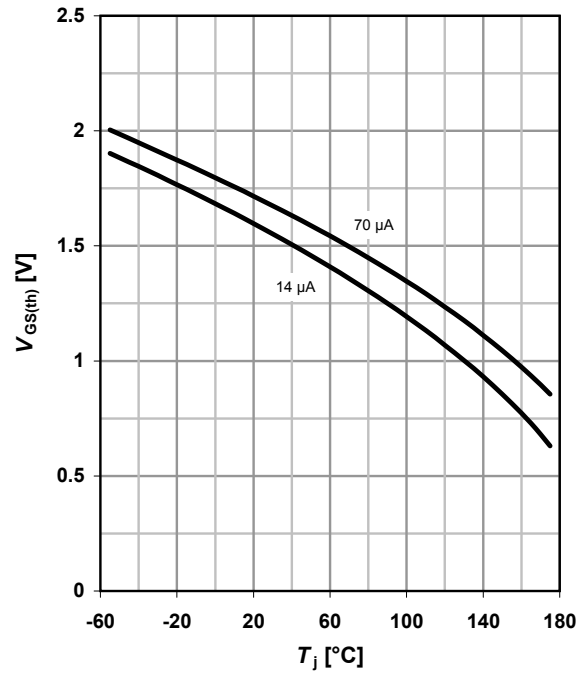


9 Typ. Drain-source on-state resistance

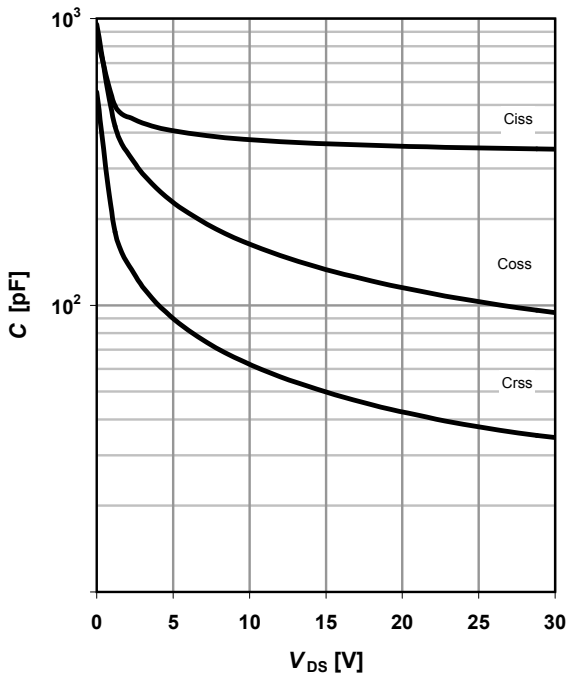
$$R_{DS(on)} = f(T_j)$$

 parameter: $I_D = 8 \text{ A}$; $V_{GS} = 10 \text{ V}$

10 Typ. gate threshold voltage

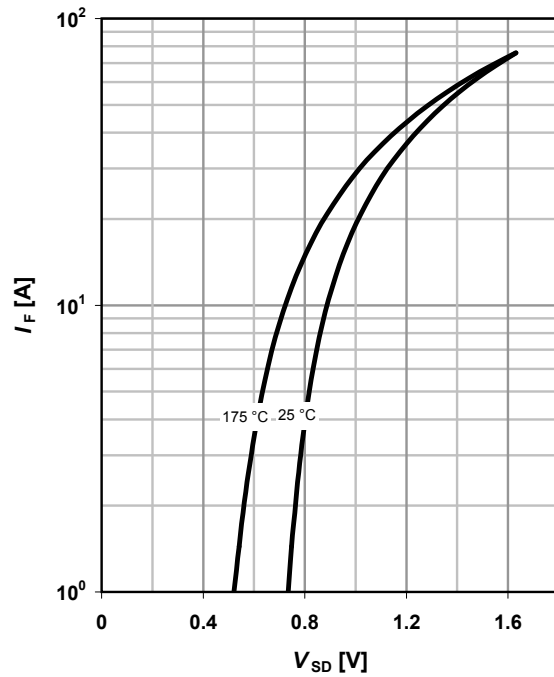
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$

 parameter: I_D

11 Typ. capacitances

$$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$$


12 Typical forward diode characteristics

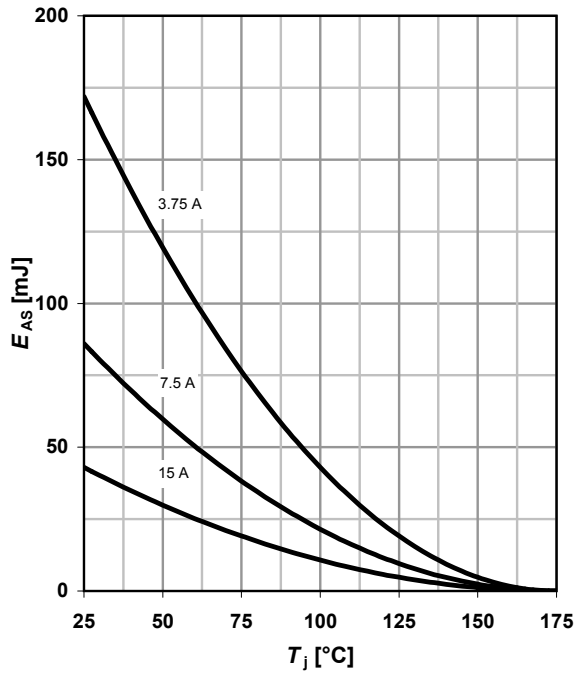
$$I_F = f(V_{SD})$$

 parameter: T_j


13 Typical avalanche energy

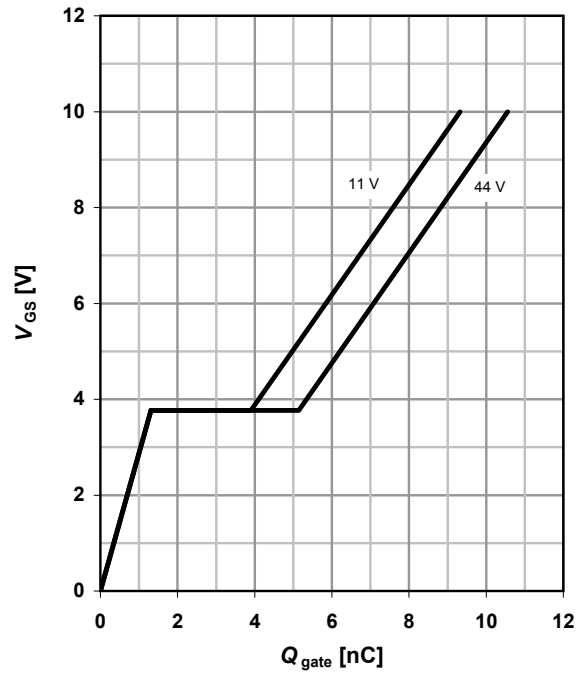
$$E_{AS} = f(T_j)$$

parameter: I_D



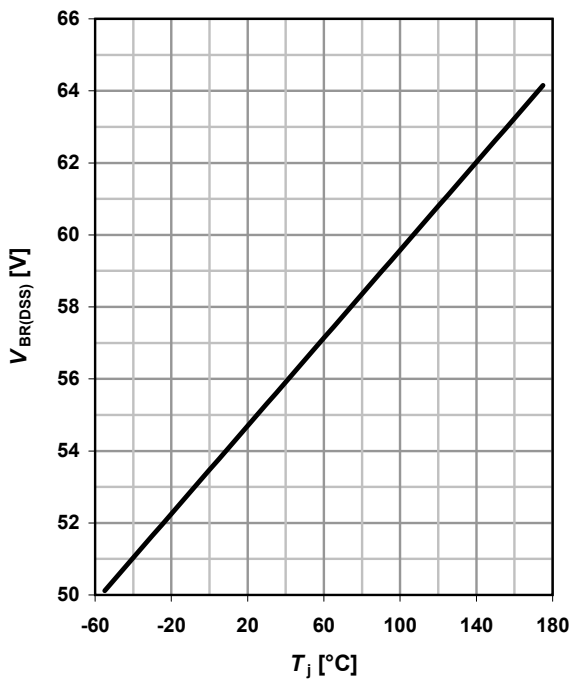
14 Typ. gate charge

$$V_{GS} = f(Q_{gate}); I_D = 19 \text{ A pulsed}$$

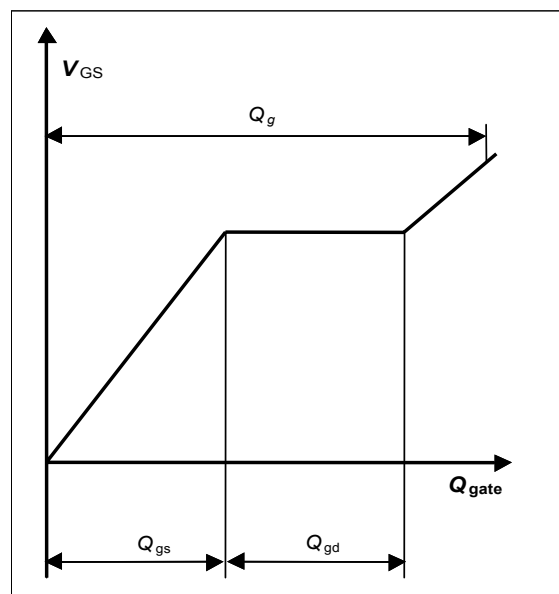


15 Typ. drain-source breakdown voltage

$$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$$



16 Gate charge waveforms



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